

Proximity Effect in E-Beam Lithography

Overview and Agenda

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Part	Subject	Date
1	Electron Scattering and Proximity Effect	07-Oct-2020, 6:00pm CEST, 12:00pm EDT, 9:00am PDT
2	Dose PEC Algorithm and Parameter	14-Oct-2020, 6:00pm CEST, 12:00pm EDT, 9:00am PDT
3	Optimization of Dose PEC Parameter	21-Oct-2020, 6:00pm CEST, 12:00pm EDT, 9:00am PDT
4	Process Effect, Calibration and Correction	28-Oct-2020, 5:00pm CET, 12:00pm EDT, 9:00am PDT
5	Shape PEC – “ODUS” Contrast Enhancement	04-Nov-2020, 6:00pm CET, 12:00pm EST, 9:00am PST
	Break	11-Nov-2020 -- No Session
6	3D Surface PEC for greyscale lithography	18-Nov-2020, 6:00pm CET, 12:00pm EST, 9:00am PST
	Thanksgiving Week	25-Nov-2020 -- No Session
7	T-Gate PEC	02-Dec-2020, 6:00pm CET, 12:00pm EST, 9:00am PST

- The webinar series will explain one of the most important techniques in advanced e-beam lithography. Modern E-beam systems are able to form small spot sizes in nm range. In principle this enables to achieve feature sizes in nm-range. In practice this is limited by physics, chemistry and tool limitations...

Proximity Effect in E-Beam Lithography

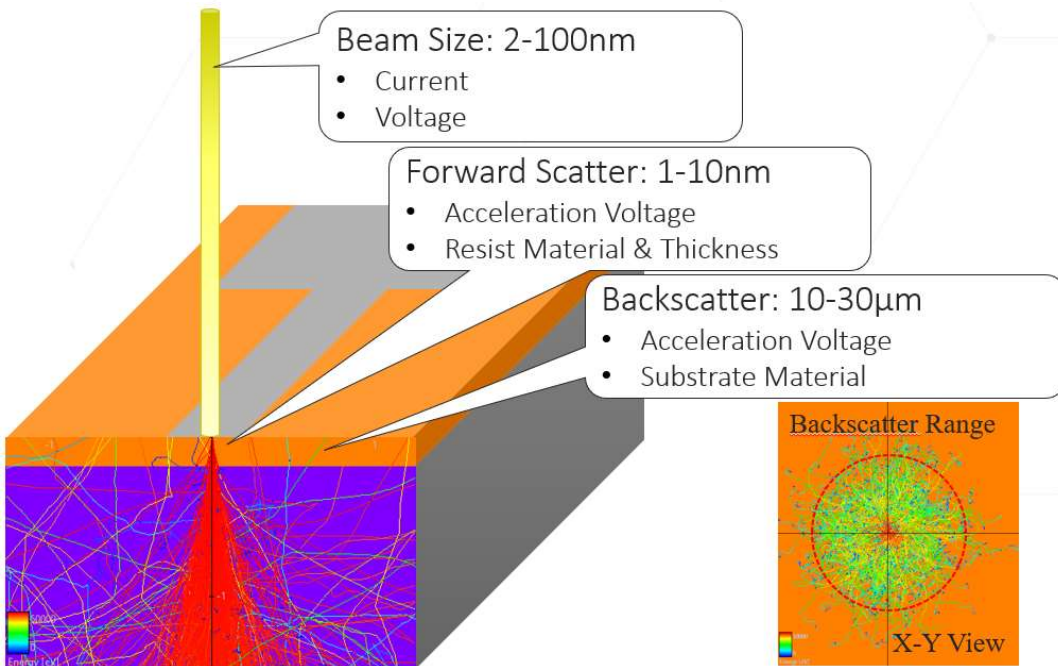
Part 2: Dose PEC Algorithm and Parameter



- Part 1 Summary: Electron Scattering & Proximity Effect
- Proximity Effect Correction Principle
- PEC Algorithm
- Main PEC parameter
- Summary + Q&A

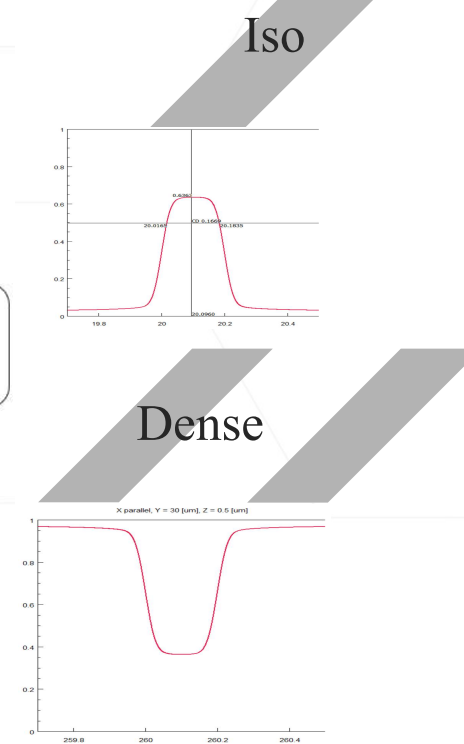
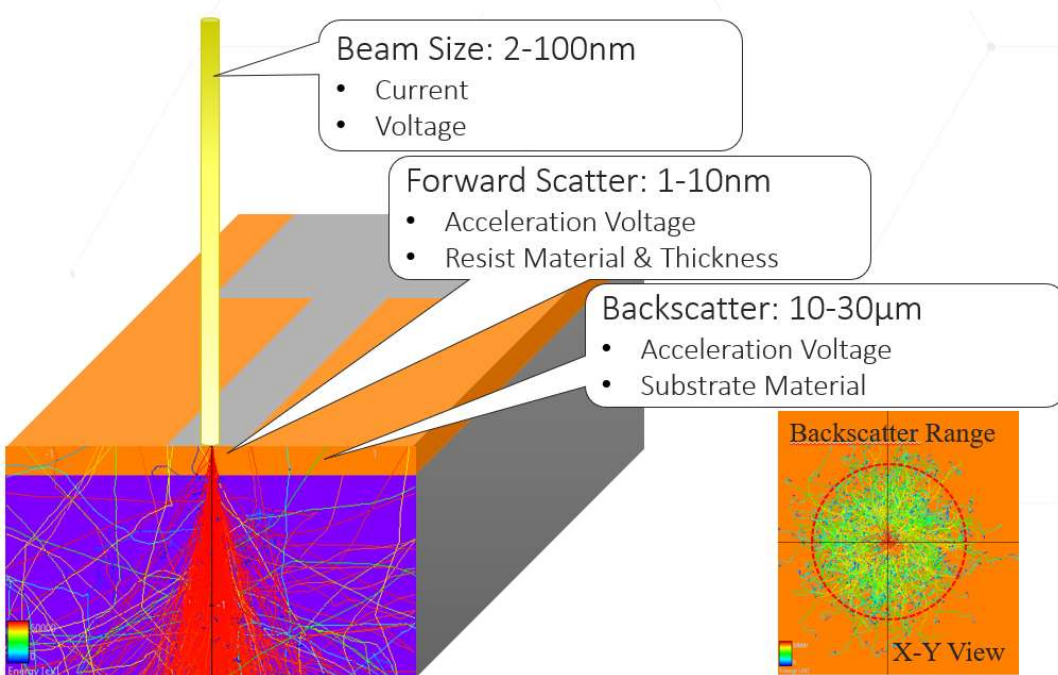
Exposure → Scattering → Printed Feature

- Proximity Effect has major influence on e-beam lithography
 - Electron scattering in the material (resist, layers, substrate) spreads the energy
 - Strength and influence ranges depend on material and acceleration voltage



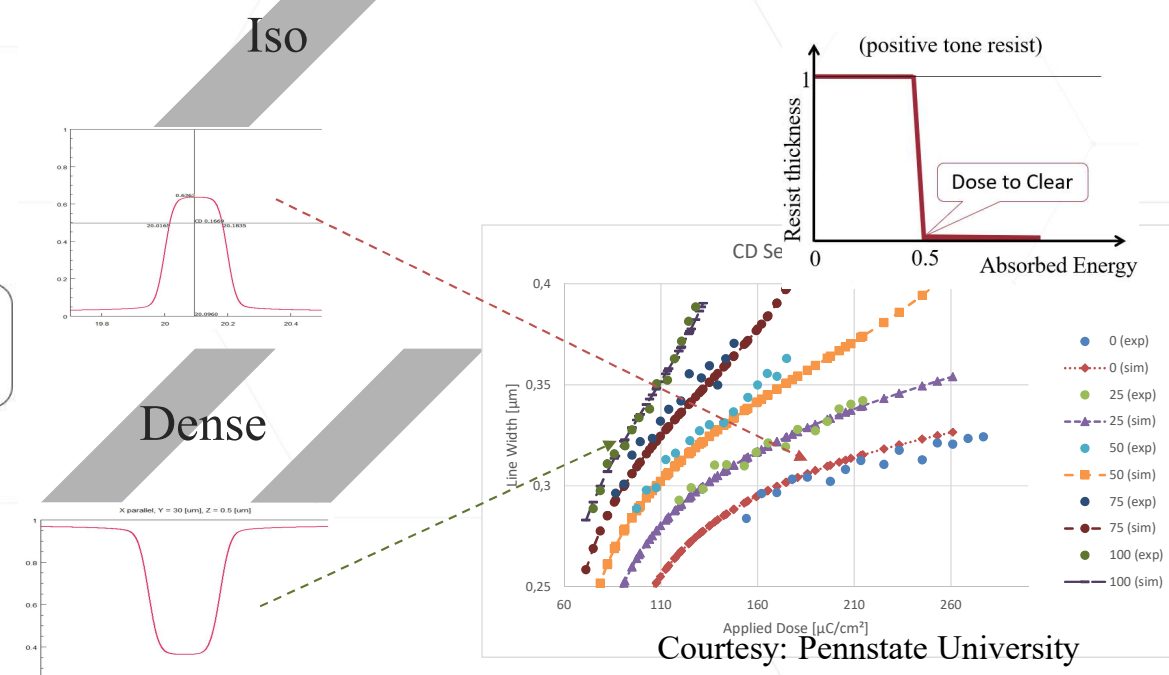
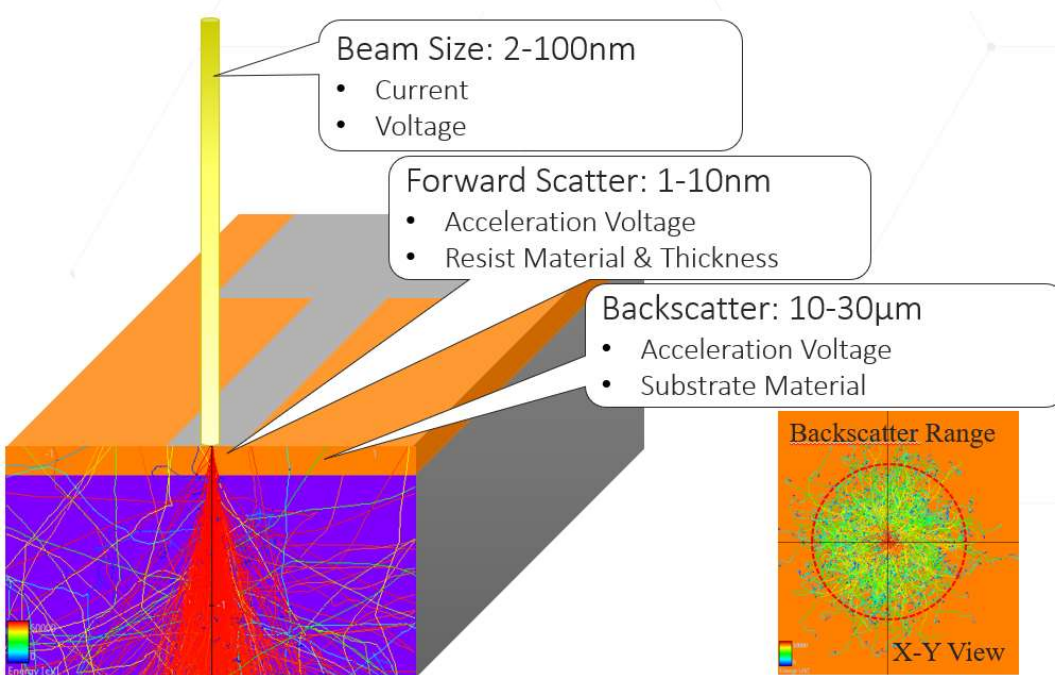
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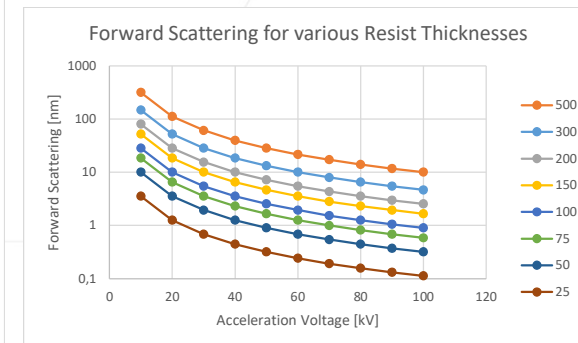
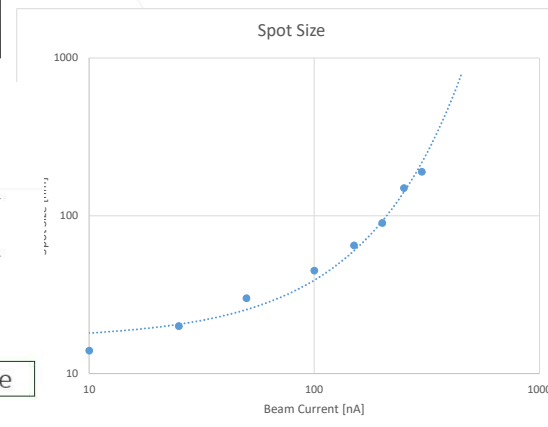
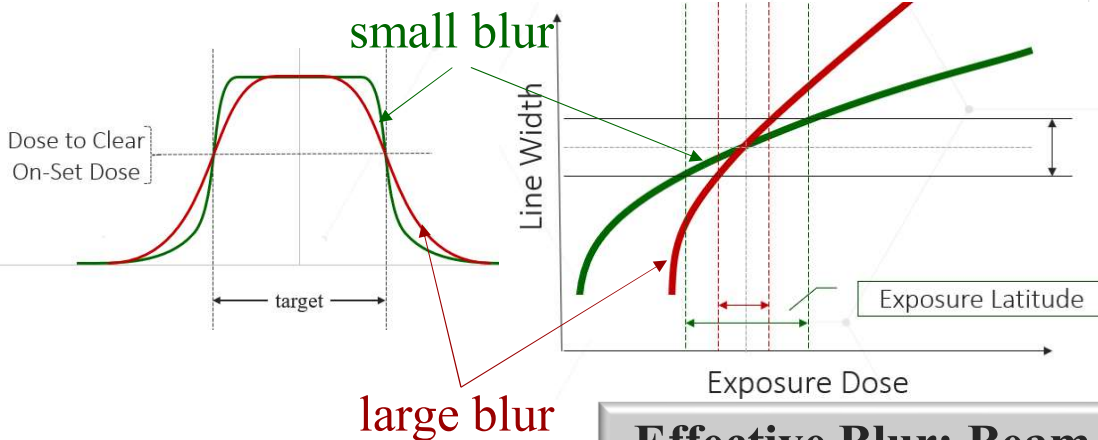
Scattering → Absorbed Energy → Printed Feature

Blur couples Dose to CD

- Impact of proximity effect on lithography result depends on tool + process parameters
 - The effective short range blur transfers absorbed energy variation to CD variation
 - The effective beam size depends on e-beam tool parameters
 - beam current, aperture, focus (variation), noise
 - Reasonable exposure time and exposure quality ask for higher beam current
 - The process (specifically resist) is another contributor to effective short range blur

Absorbed Energy

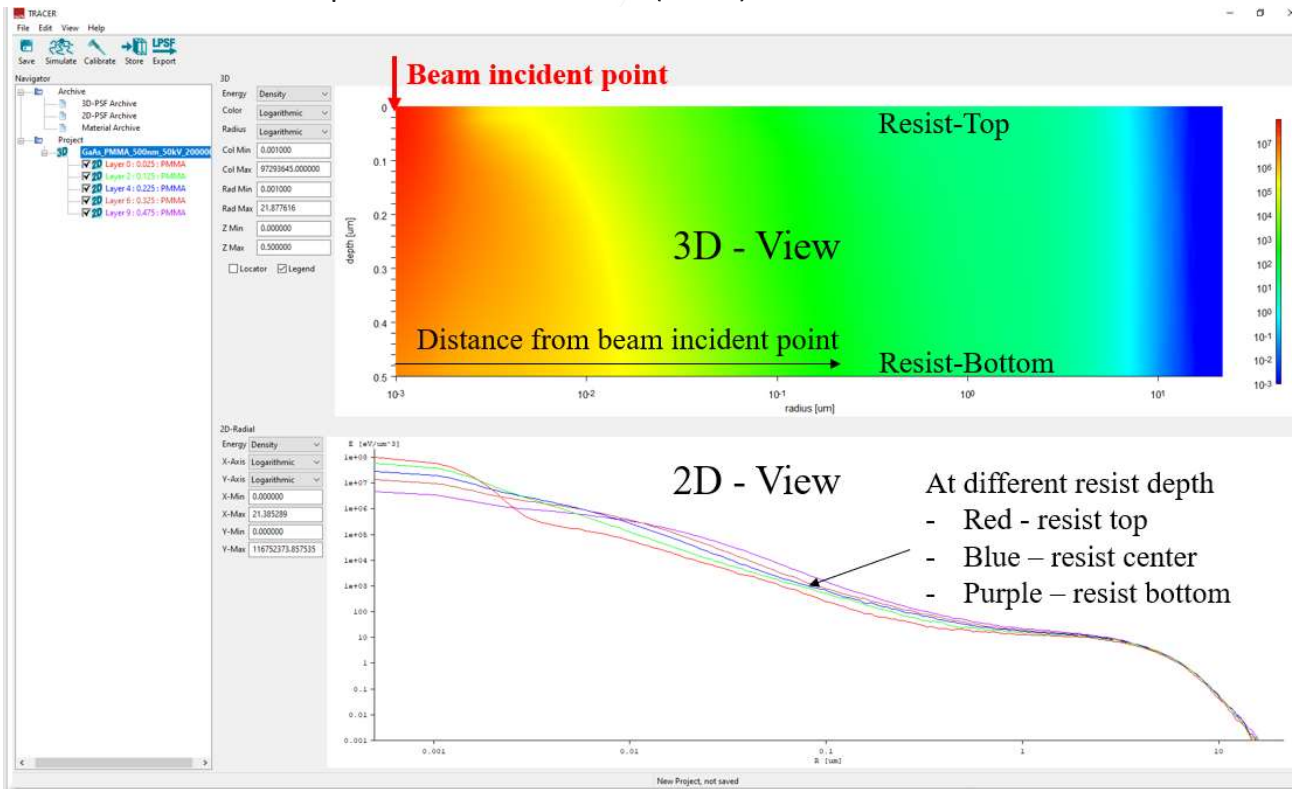
CD Sensitivity to Dose



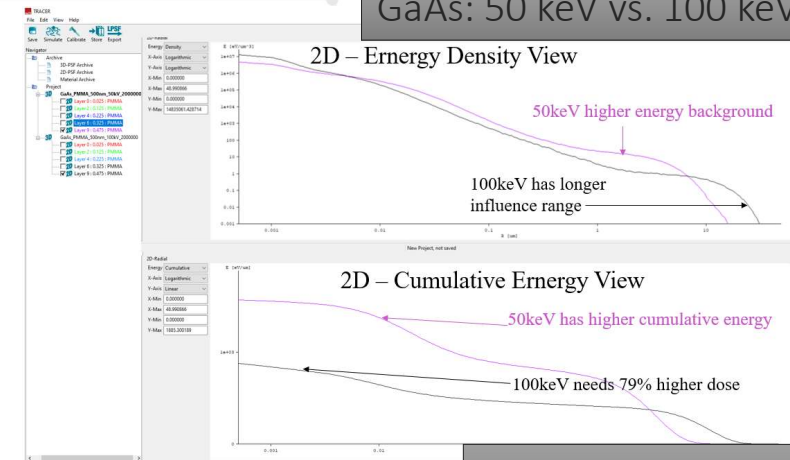
Effective Blur: Beam Size + Scattering + Process

Electron Solid Interactions (Scattering)

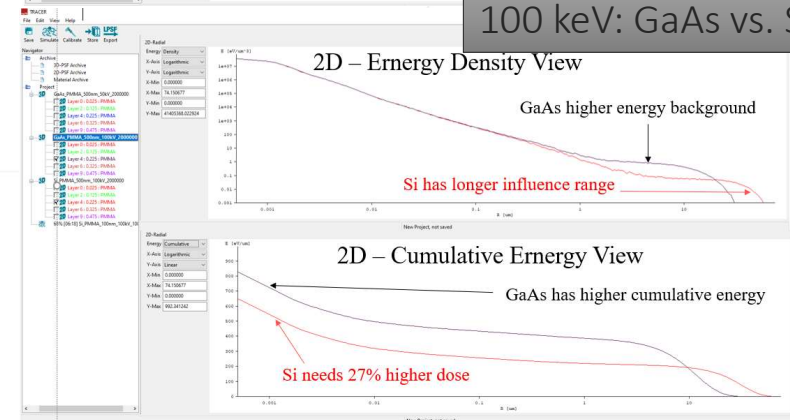
- Monte-Carlo Simulation is an excellent technique to model electron scattering
 - Point Spread Function (PSF) for different stacks and acceleration voltages



GaAs: 50 keV vs. 100 keV

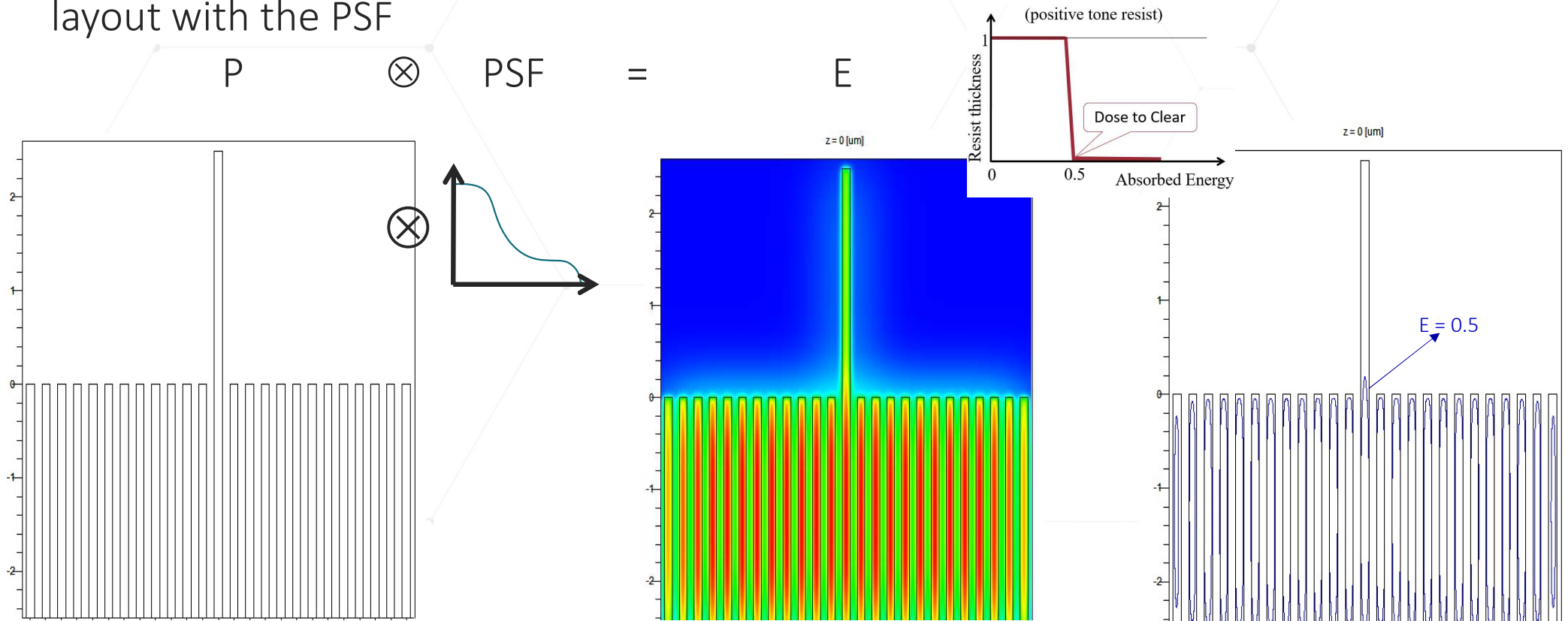


100 keV: GaAs vs. Si



Baseline Simulation Mechanism

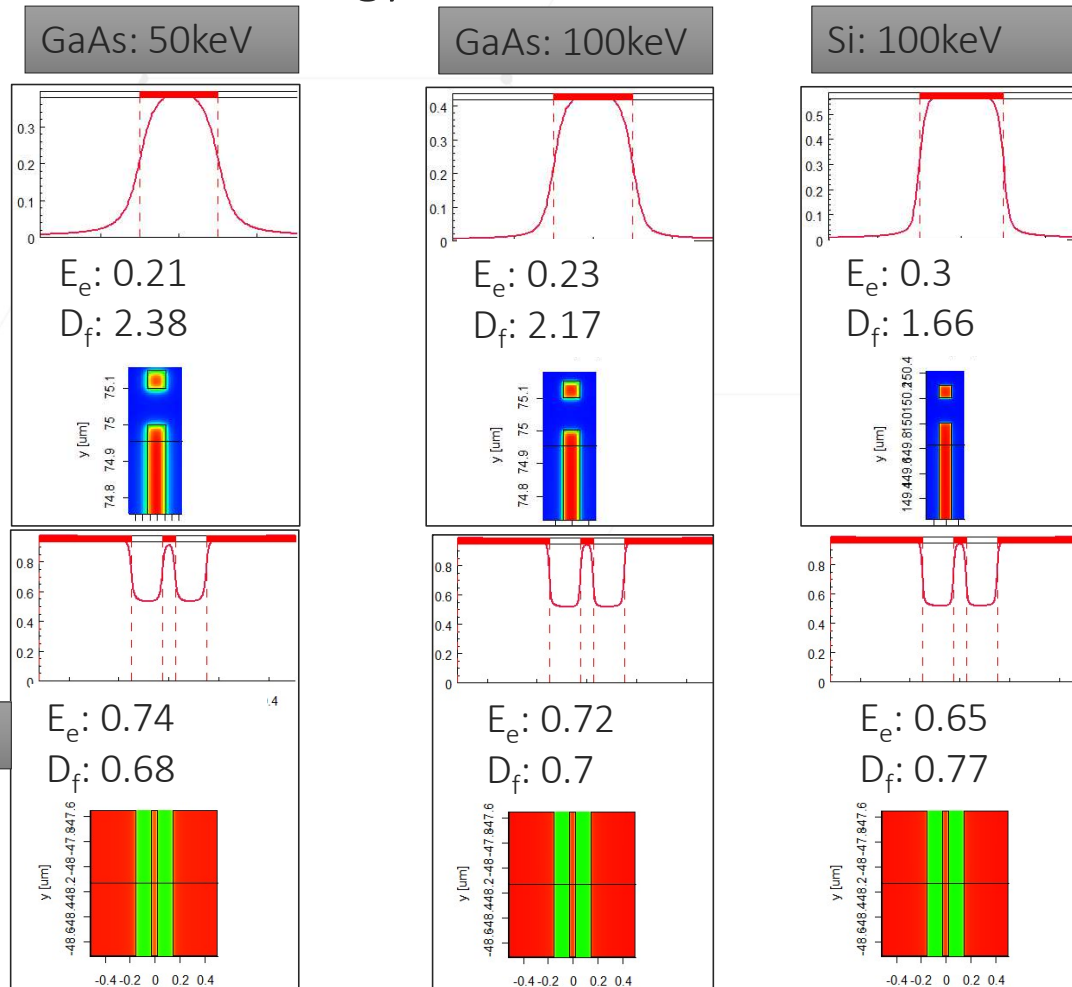
- Absorbed energy and resist contour at D2C can be simulated by convolution of the layout with the PSF



Threshold already provides 1st order indication of printed feature

Simulation Extended

- Absorbed energy at Iso & Dense for different stacks end acceleration voltage



- Absorbed energy at the layout edge (E_e) is varying depending on layout density (iso and dense), leading to layout dependent CD
- Consequently layout density dependent dose factor will be needed to adjust all feature edges to the same absorbed energy (dose to clear)
- The dose factors depend on acceleration voltage and stack (mainly substrate material density)

How to get these Dose Factors

- One can
 - Determine iso / dense dose factors experimentally
 - Alternatively determine iso / dense dose factors by simulation
 - Manually apply these to the pattern (including fracturing of critical geometries)
 - Redo this process for each pattern / process change / V_{acc} change / stack change
- Or
 - Use an algorithm to do the job for you
 - and invest in a characterized base line process
- Makes your life so much easier



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Lithography

- Part 1 Summary: Electron Scattering & Proximity Effect
- Proximity Effect Correction Principle
 - Constraints
 - Edge Equalization
 - Benefits of PEC
- PEC Algorithm
- Main PEC parameter
- Summary + Q&A

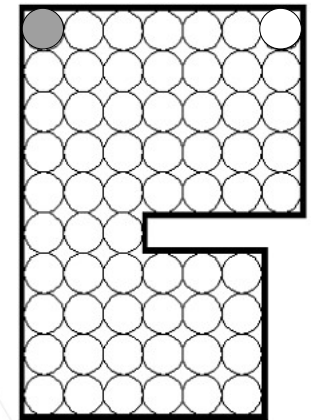
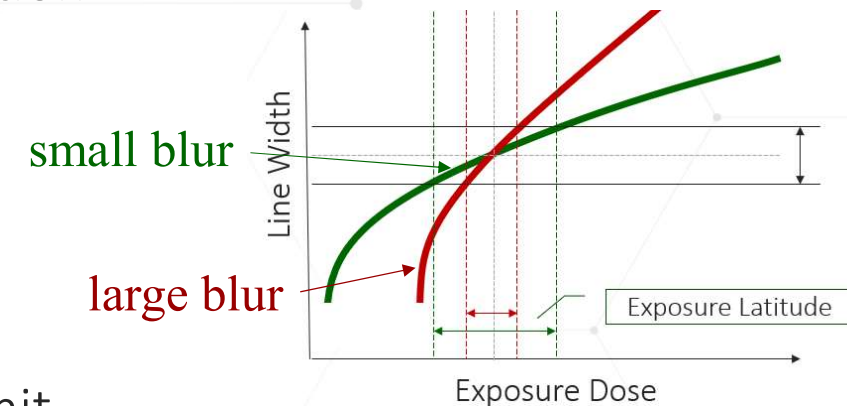
Correction Principles

- e^- -Scattering → Dose Errors → CD Errors (effective blur)
 - 1000's of paper discussed a multitude of aspects
- Degree of Freedom (what to modulate)
 - Shape, Dose, or a combination of both
- Correction Target (what to optimize for)
 - Algorithmic: Linear Operator, Area Equalization, Edge Equalization
 - Machine Learning
- Algorithms (how to compute this)
 - Iterative Inverses (e.g. Newton Inverse), Ghost (1st order Inverse)
 - Approximate Solutions
 - Linear Optimization

Each one would deserve its own tutorial

- „Best practice“
 - Dose errors should be corrected by dose modulation
 - Shape errors should be corrected by shape
- Rationale
 - Dose correction can be blur independent
 - Shape correction only works for ONE blur
 - Dose correction does not introduce resolution limit
 - Amount of Shape modulation limited by smallest feature / gap
 - Tools allow reasonable fine dose control (both GB and VSB)
 - Shape Modulation only in increments of Shot Pitch (Shape Fill)
 - Exception: Shape modulation can help in contrast limited scenarios
 - E.g. undersize / overdose...

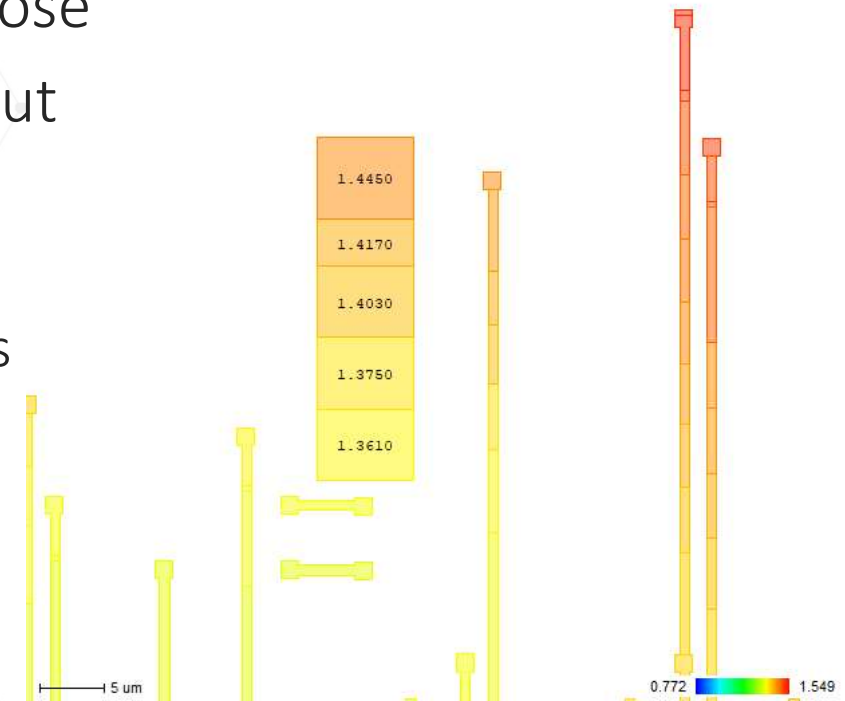
Dose vs. Shape



Standard e⁻-scattering PEC is best corrected via dose modulation

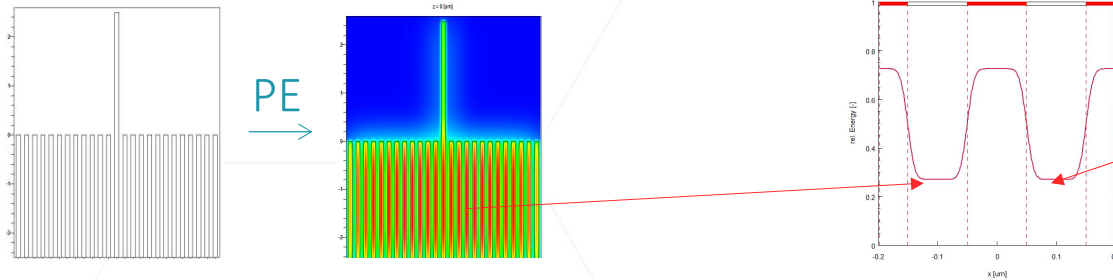
Side Note: PEC Fracturing

- Tools can expose one shape only with ONE dose
- Therefore, a dose PEC must fracture the layout in areas / shapes of equal dose
- Leads to another tradeoff
 - Fewer shapes: less overhead, coarse grain doses
 - More Shapes: more overhead, fine grain doses



1. D. Kern, A novel approach to proximity effect correction, Proc. Symp. On Electron and Ion Beam Science and Technology, 9th Int. Conf., Vol. 80-6, pp. 326-339 (1980)
2. G. Owen and P. Rissman, Proximity effect correction in electron beam lithography by equalization of background dose, J. Appl. Phys., 54(6), 3573-3581 (1983)
3. R. Crandall et al, Contrast Limitations in Electron-Beam Lithography, EIPBN 1999
4. M. Parikh, Corrections to proximity effects in electron beam lithography, J.Appl.Phys., 50(6), 4371-4377 (1979)
5. H. Eisenmann et al, PROXECCO – Proximity Effect Correction by Convolution, J.Vac.Sci.Technol., B Vol.11, No.6, Nov/Dec 1993
6. J. Pavkovich, Proximity effect correction calculations by the integral equation approximate solution method, J. Vac.Sci. Technol., B, Vol.4, No.1, Jan/Feb 1986
7. T. Abe et al, Fast and Highly accurate Proximity Effect Correction for Mask Making, 3rd International Workshop on High Throughput Charged Particle Lithography, Hawaii, 1998

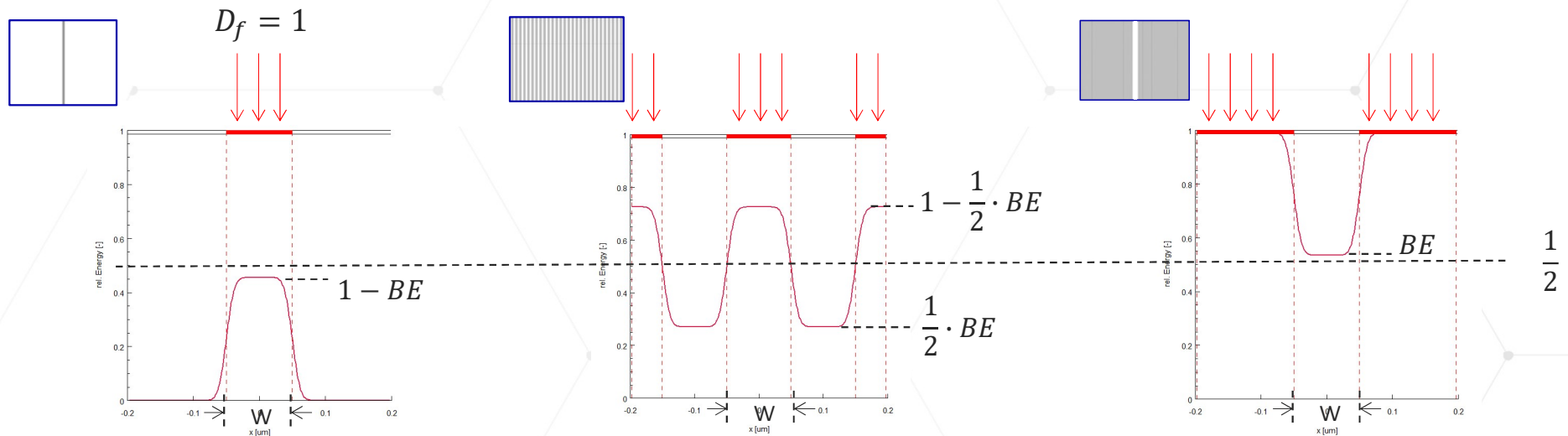
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e^- in gaps cannot be „sucked out“
would require positrons...

- Proximity Effect (Blur) is like a diffusion.
- Due to “information loss” the process can not be inverted!
- Prior linear (convolution based) PEC approaches, e.g. Ghost, deconvolution had shortcomings.
- So the more generic goal of PEC becomes the equalization of dose discrepancies across the layout.
- The correction result strongly depends on a thoroughly chosen target definition.
- Subsequently the (non-linear) edge equalization target PEC is discussed.

Three limiting cases illustrating the proximity effect



Case 1. Narrow line ($w \ll \beta$)

Case 2. Lines & Spaces (50%)

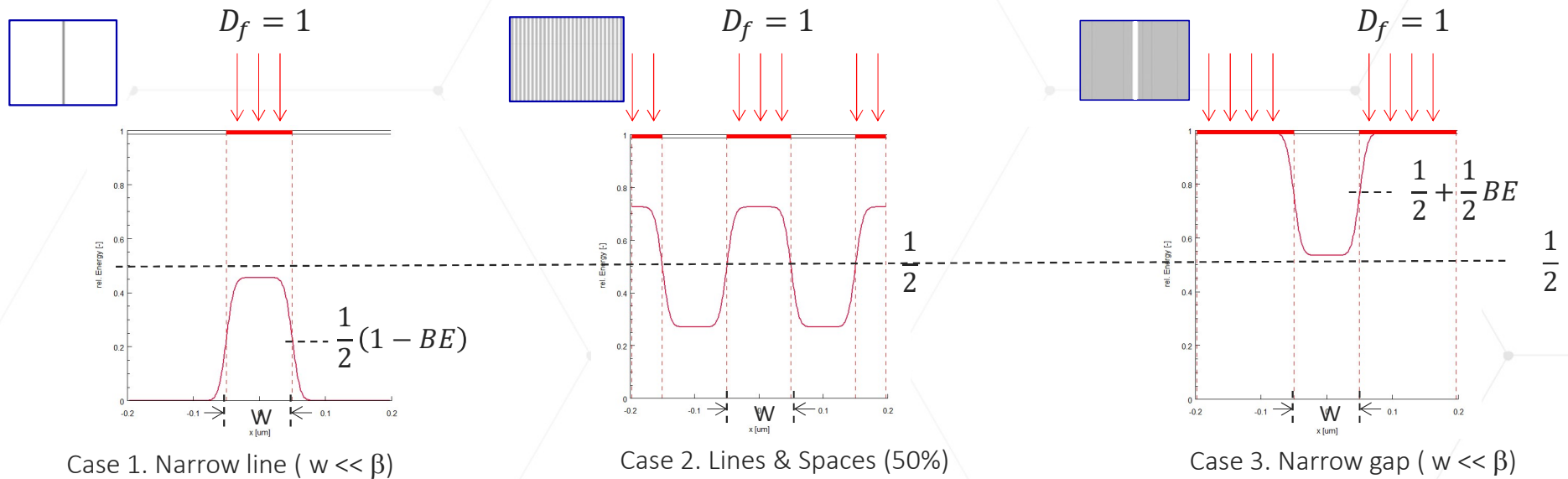
Case 3. Narrow gap ($w \ll \beta$)

Fig. Three limiting cases illustrating the proximity effect. Pavkovic, j: Vac. Sci. Technol. B 4 (1), 86

• Glossary:

- BE: Backscattered Energy
- FE: Forwardscattered Energy
- $BE + FE := 1$
- D_f : Applied Dose Factor

Three limiting cases illustrating the proximity effect



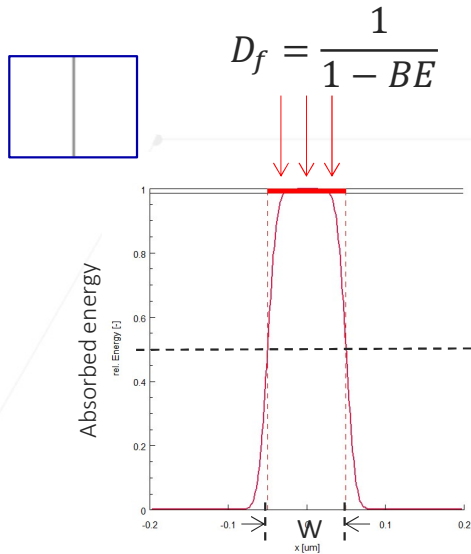
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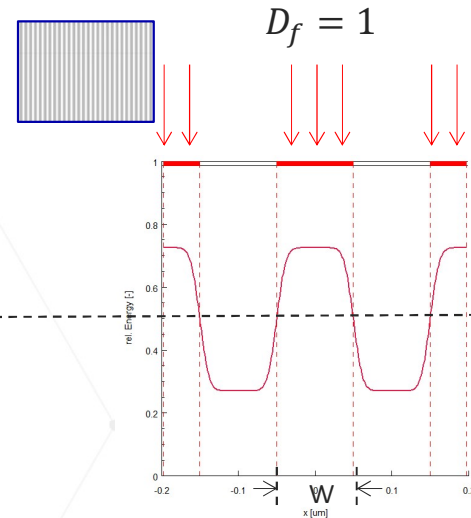
- **Edge Equalization** → Adjust the dose the way that :

- Exposed area Dose > D2C (Dose to Clear)
- Unexposed area Dose < D2C.
- Target : D2C dose @ all edges

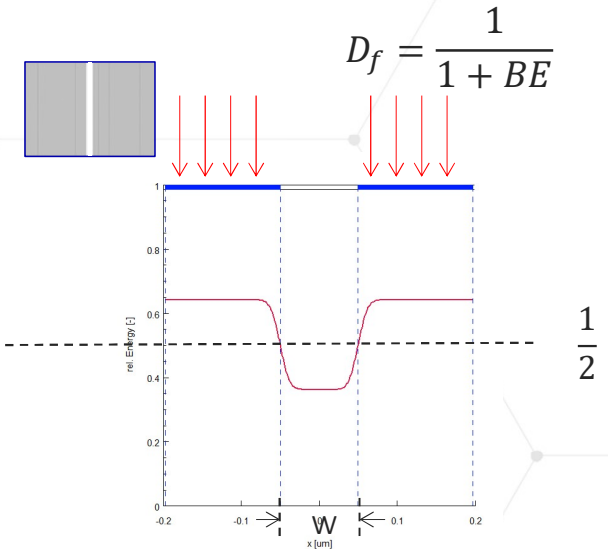
Edge Equalization is blur independent



Case 1. Narrow line ($w \ll \beta$)



Case 2. Lines & Spaces (50%)

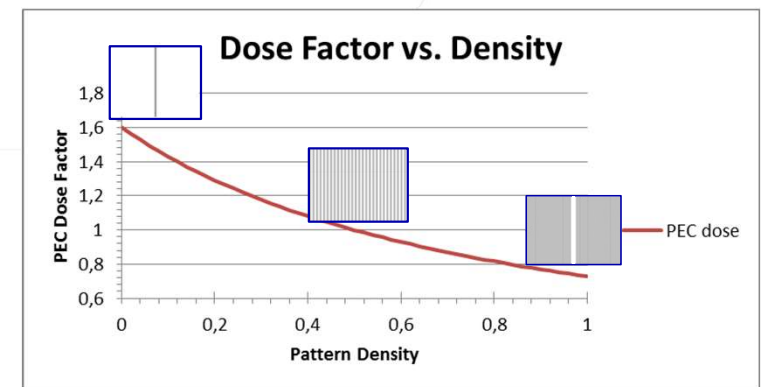


Case 3. Narrow gap ($w \ll \beta$)

NOTE: DTC @ Edge \rightarrow Isofocal point!

$$D_f \cdot \left\{ \frac{1}{2} \cdot FE + \rho \cdot BE \right\} = \frac{1}{2} \quad \rightarrow \quad D_f = \frac{1}{1 + BE(2\rho - 1)}$$

ρ : long range pattern density



Mix Factor

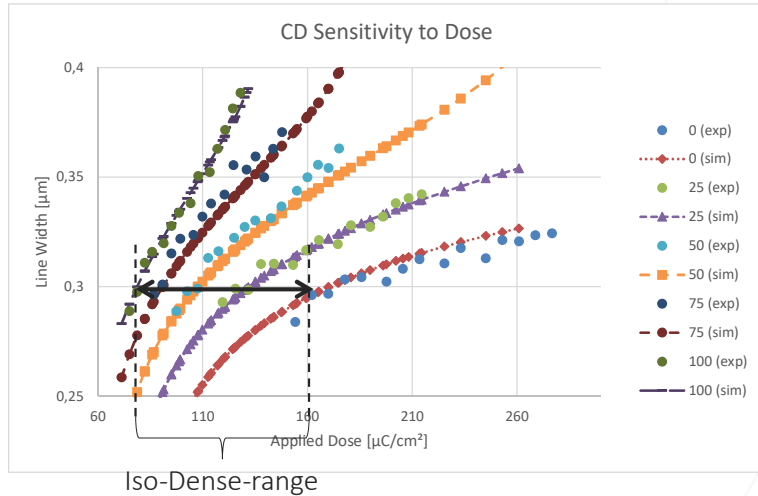
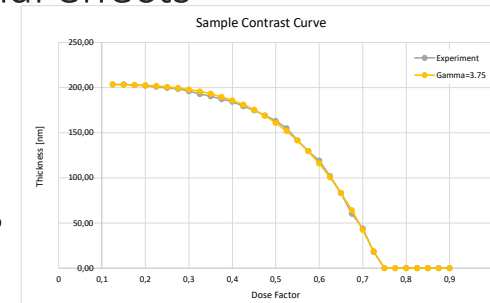


Fig. CD sensitivity to Dose. Showing the Iso to Dense dose range; By courtesy of Pennstate Univ.

- Edge equalization (iso-focal) works well for high-contrast resists
- Low contrast resists ($\gamma \leq 3$) add additional effects
 - E.g., lateral development changes CD
 - As a result, required doses change
- PEC can take into account lateral Biases
 - Alternatively, adopt dose range to process



$$D_f = \frac{1}{1 + BE((1 + mf) \cdot \rho - 1)}$$

In order to make the dose range tunable the mix factor **mf [0:1]** is introduced.

0: uniform clearing

1: optimal contrast \triangleq edge equalization (default)

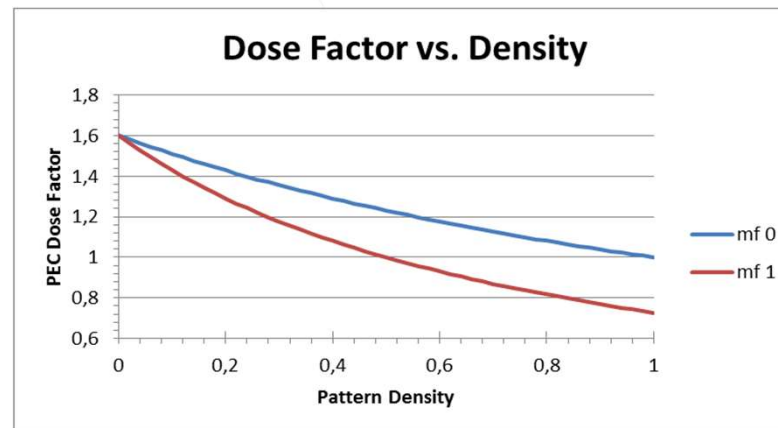


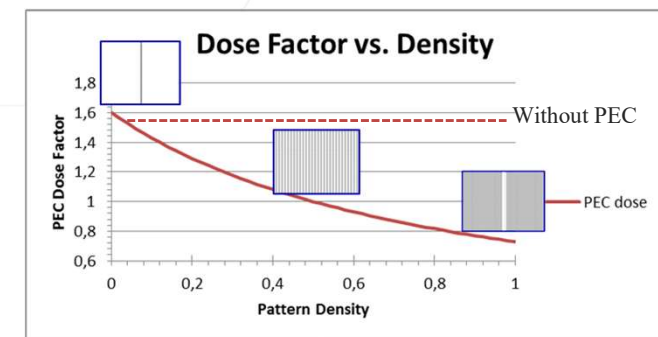
Fig. Dose factor vs. density for the limiting mix factors. (BE = 0.375)

$$\theta = \theta_0 * \left(1 - \left(\frac{D}{D_0}\right)^\gamma\right)$$

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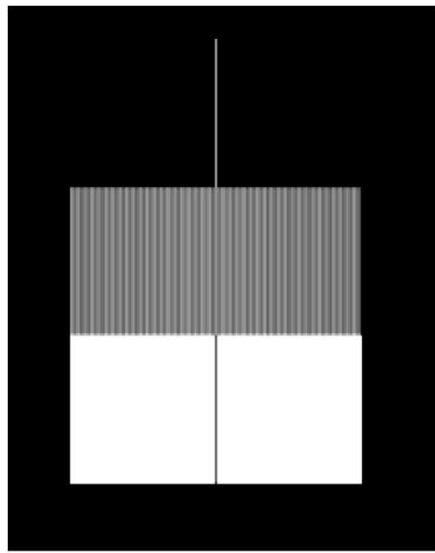
- Process portability
 - No dose matrices for setup
 - Takes out pattern dependence
 - Easily transferable to other stacks / voltages
- CD linearity (also density dependent)
- Opens / enlarges process window
- Dose Latitude (Contrast) enhancement for sparse features
- Pixel time reduction

Benefits of PEC

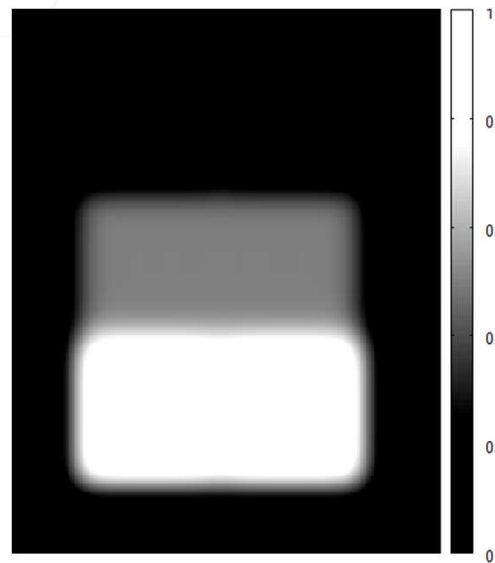


- Part 1 Summary: Electron Scattering & Proximity Effect
- Proximity Effect Correction Principle
- PEC Algorithm
 - Principle algorithm
 - Long-, Mid-, Short-Range
- Main PEC Parameter
- Summary + Q&A

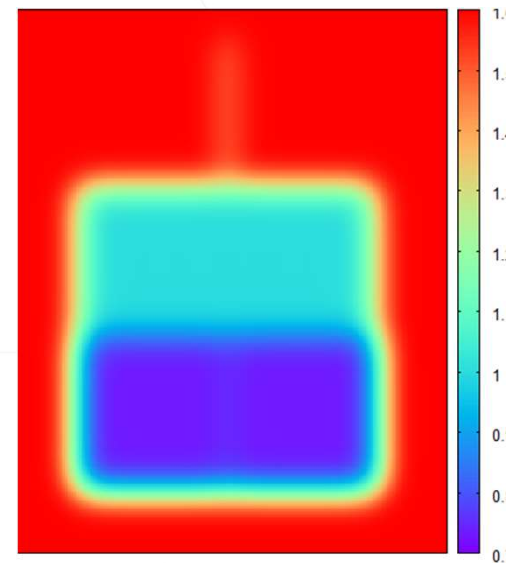
Back-Scatter PEC: Pixel Based



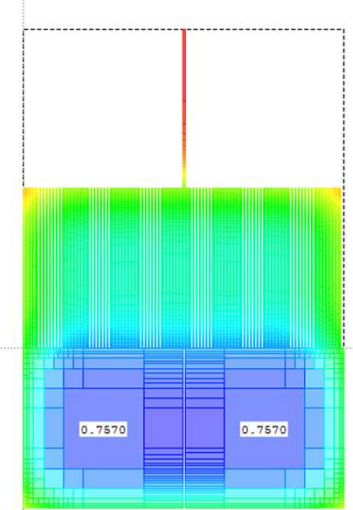
A. Original Layout as bitmap



B. Convolved pattern density



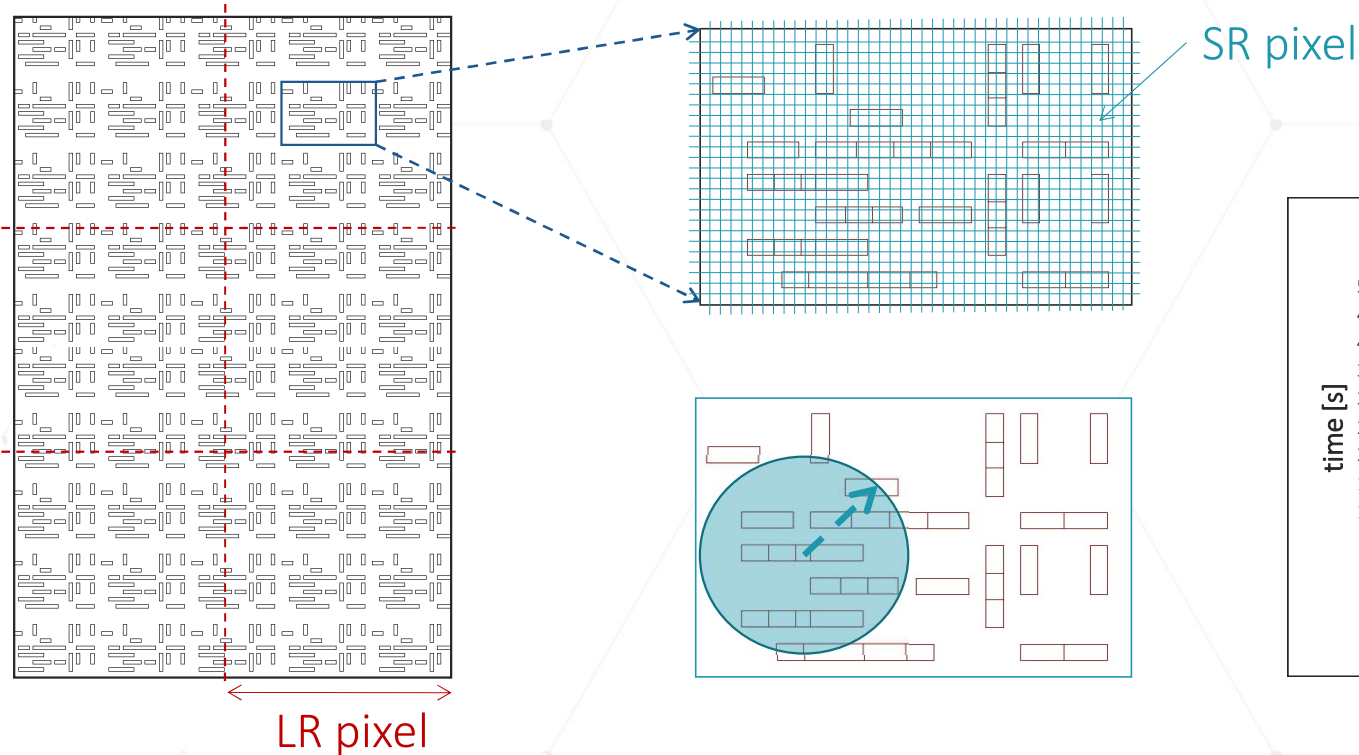
C. Correction dose map



C. Dose transfer to polygonal data including physical fracturing

- Fast (applicable to large layouts in reasonable times) -> Pixel based -> FFT
- Stable and robust
- Physical Fracturing

Influence Range \Leftrightarrow Algorithm Choice



- Due to the range discrepancy the required SR pixel size would be $\sim 1/1000$ compared to LR!
- Complexity increase: 1000^2
- Conclusion: SR pixel based computations are feasible only for simulation of small samples but not for PEC.

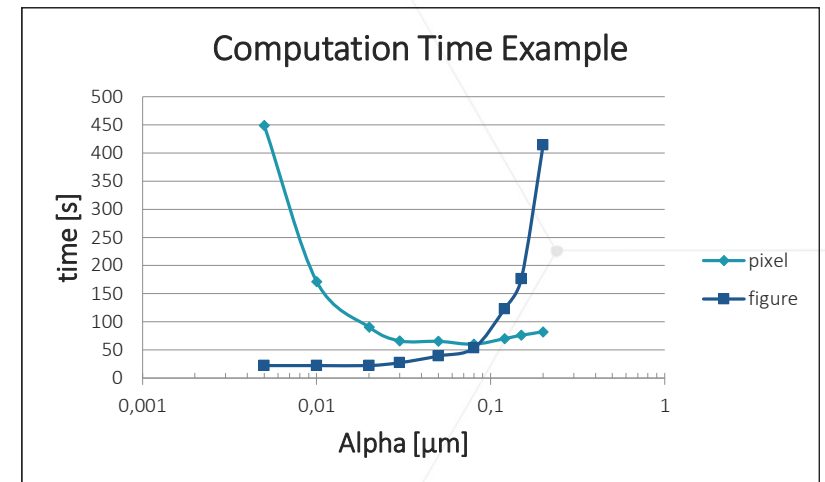
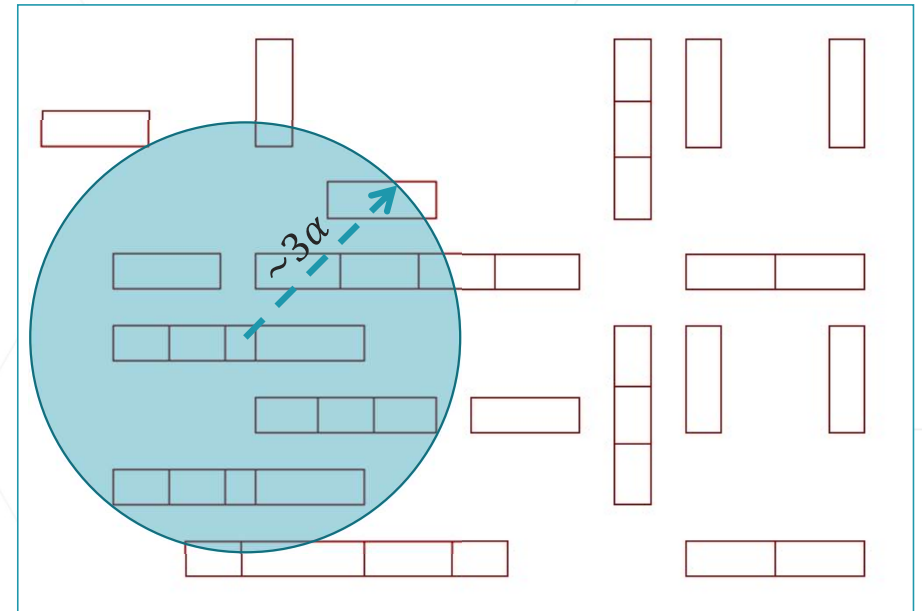


Fig. PEC test runs, measured performance for pixel- and figure based algorithms. Variable alpha parameter, beta = $30\mu\text{m}$, eta = 0.6, Beam-blur $0.01\mu\text{m}$. Design: Array of 375000 squares of $0.024\mu\text{m}$ width.

- Using a self consistent method for the compensation of the short range effect is favorable as the complexity is proportional to the average neighbor count (ANC) which is per se small in a short range vicinity.
- Complexity: $O(N * ANC(\alpha))$
- In order to boost performance a DRC is performed to identify SR PEC relevant areas.

Short Range PEC



- Mid Range (MR) PEC is the computationally most challenging.
 - If feasible it is included either in SR or LR.
 - If not it is performed on a finer grid.

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 - PSF selection, Base Dose, Effective Blur
- Summary + Q&A

- PSF
 - Use Monte Carlo PSF's
- Effective Blur
 - Including: forward scattering (α), beam blur and resist effects.
 - 1st order estimate:
 - $FWHM = 0.76 * \Delta CD / \Delta \%dose$ ¹⁾
- Base Dose
 - ~ 2 x Dose to Clear
 - Simple way: Dose Matrix on one PEC'd pattern
- Dose Classes / Fracturing
 - Recommended Dose Accuracy: 3%
 - Min. Fracturing Size

Main PEC Parameters

- Dose Error
 - Influence of a dose deviation on an edge position: extracted from the computed edge position shift.
 - According to the linear edge model the CD error can be approximated by:
 - $\Delta CD = (FWHM / 0.76) \Delta \%dose$ ¹⁾
 - Example: $\Delta CD = (50nm / 0.76) * 3\% = 2nm$
- Please note: reducing dose accuracy for 2D PEC might even improve results
 - CD change can be minimal (see formula)
 - Especially consider to avoid MR parts if the contribution is small
- Remark 1: the 0.76 factor is the same factor used for spot size measurements: 12% - 88% (the difference is 0.76)
 - Background: the 12-88% point of an Erf() function is the FWHM of the corresponding Gaussian

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- Always use PEC
 - No dose matrices needed, applicable for all patterns, ...
 - Opens/enlarges process window
- Edge equalization is an efficient and robust method
 - Iso-focal criteria provides best CD control also at field corners / edges
- PEC influence ranges
 - SR, LR and MR PSF parts treated differently (computational complexity)
- Basic parameters pretty simple: PSF, Effective Blur, Base Dose
- Low Contrast Resist processes may require adoption of dose range D_{iso}/D_{dense}
 - Mixed Mode: Optimal Contrast / Uniform Clearing